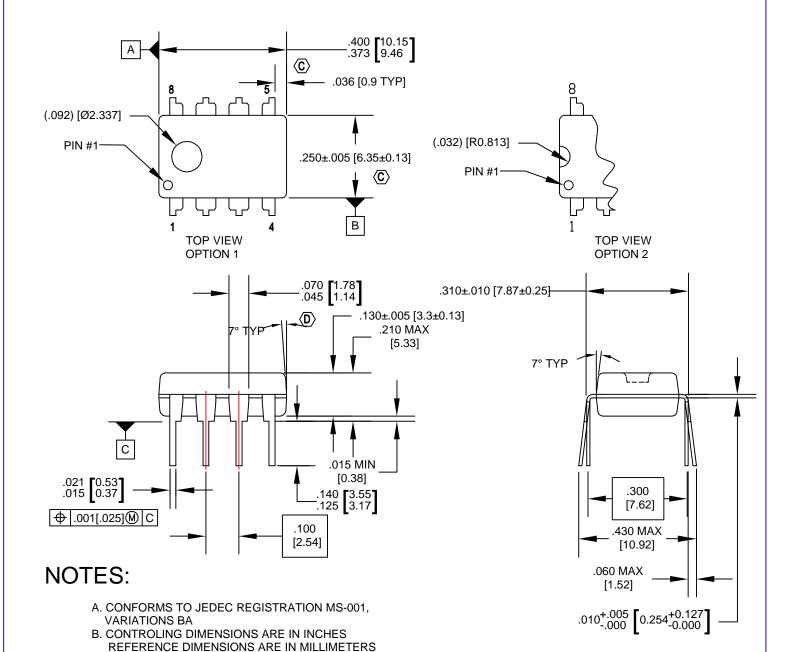
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REVISIONS										
LTR	DESCRIPTION	ECN	DATE	BY/APP'D						
G	Redraw origonal CAD file lost	ECN-MKT-N08EREVG	02-21-2006	J.KINGSBURY						



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© DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED

DDOES NOT INCLUDE DAMBAR PROTRUSIONS.

DAMBAR PROTRUSIONS SHALL NOT EXCEED

.010 INCHES OR 0.25MM.

.010 INCHES OR 0.25MM.

PER ASME Y14.5M-1994.

E. DIMENSIONING AND TOLERANCING

